

承認書

APPROVAL SHEETS

客戶名稱 : 鴻海精密工業股份有限公司
MESSRS

品名 : DC POWER JACK
DESCRIPTION

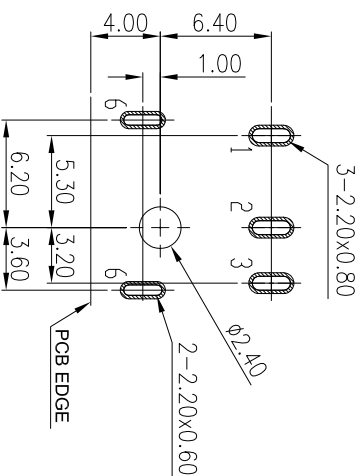
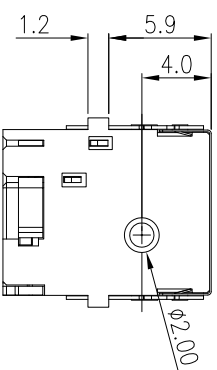
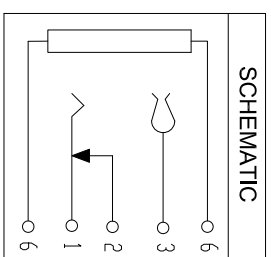
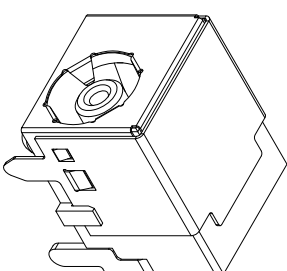
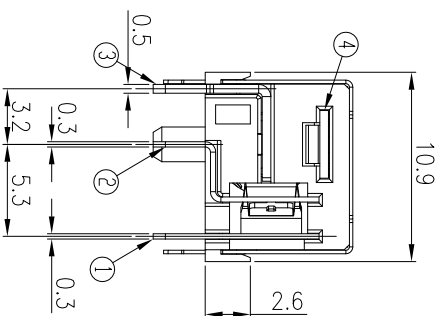
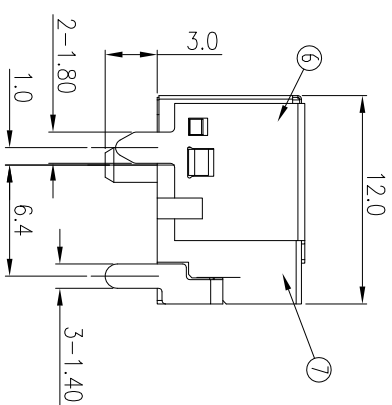
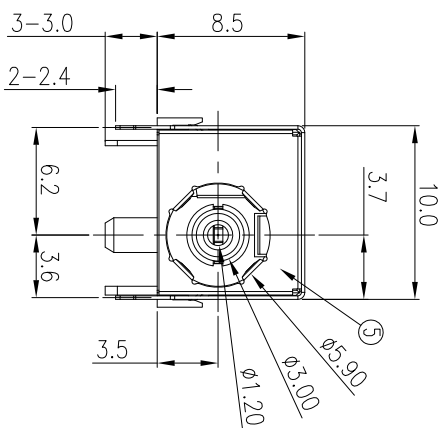
料號 : SHD-6012D01-BLTN-T1
PART NO

客戶料號
CUSTOMER :
PART NO

承認印 APPROVED BY



博 歲 電 子 股 份 有 限 公 司
POWERWAY ELECTRONICS CO., LTD.
佳 俊 有 限 公 司
BEST SMART LIMITED
2 4 1 6 1 新北市三重區中華路 18 號 3 樓
3F., No. 18, Zhonghua Road, Sanchong
District, New Taipei City 24161, Taiwan
TEL : 886-2-2986-6161 FAX : 886-2-2971-8665



RECOMMENDED PCB LAYOUT

TOP VIEW

TOLERANCE: $\pm 0.05\text{mm}$

PCB THICKNESS: $1.60 \pm 0.05\text{mm}$

7	HOUSING	THERMAL PLASTIC	COLOR BLACK
6	SHELL 2	COPPER ALLOY	NI PLATED
5	SHELL 1	ALLOY	_____
4	TERMINAL 4	COPPER ALLOY	TIN PLATED
3	TERMINAL 3	COPPER ALLOY	TIN PLATED
2	TERMINAL 2	COPPER ALLOY	TIN PLATED
1	TERMINAL 1	COPPER ALLOY	TIN PLATED
NO.	NAME	MATERIAL	FINISH

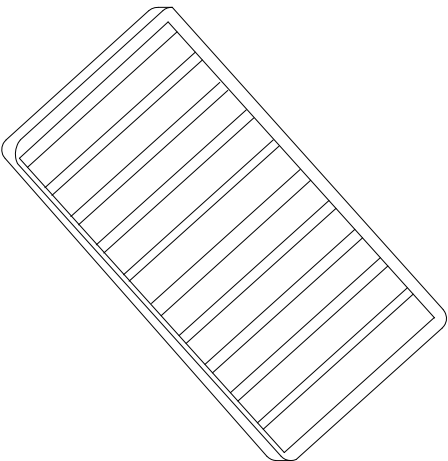
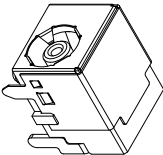
 博 威 電 子 股 份 有 限 公 司
POWERWAY ELECTRONICS CO.,LTD.

FILE NO.	SHD (SERIES)	TITLE 圖名	DC JACK	DESIGNED	Alas
PART NO					

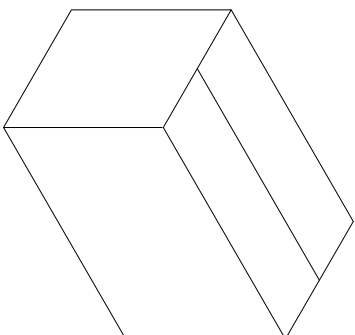
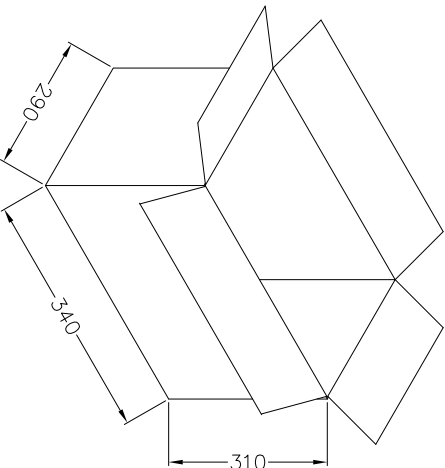
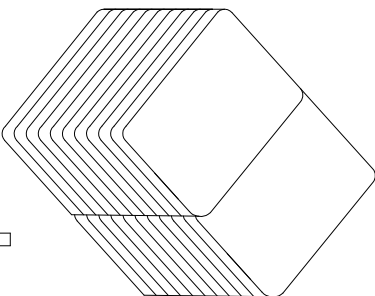
ZONE	REV.	DESCRIPTION	DATE	CHANGE

		料 號		SHD-6012D01-BL.TN-T1		DESIGNED BY		2020-07-14	
TOLERANCE(公差): 0,000 mm ± 0,15 mm 0,00 mm ± 0,25 mm 0,0 mm ± 0,35 mm		UNIT		mm	REV. 版 本	A.0	CHECKED BY	Sword	2020-07-14
		單 位	SCALE 比 例						

1. 包材: 吸塑盒 1 PC
數量: 1*130=130 PCS
PACKING MATERIAL: TRAY 1 PC
Q' TY: 1*130=130 PCS



2. 包材: 外箱 1 PC
數量: 130*42=5460 PCS
PACKING MATERIAL: CARTON 1 PC
Q' TY: 130*42=5460 PCS



裝外箱OK

淨毛重
單位(KG)
數量
單位(PCS)

P / N	N.W.	G.W.	QTY
SHD-6012D01-BL.TN-T1	9.4Kg	13.5±0.3Kg	5460

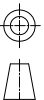


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FILE NO.	SHD (SERIES)	TITLE	SHD-6012D01-BL.TN-T1 包裝規範
PART NO. 料 號	SHD-6012D01-BL.TN-T1	DESIGNED BY	DdI 2020-07-14

UNIT 單位	mm inch	REV. 版本	A.0	CHECKED BY	Jay 2020-07-14
SCALE 比例	1:1	SHEET 頁次	1/1	APPROVED BY	Jay 2020-07-14

TOLERANCE(公差):
0.000 mm ± 3.00 mm
0.00 mm ± 6.00 mm
0.0 mm ± 10.00 mm



ZONE	REV.	DESCRIPTION	DATE	CHANGE
1	1			



DC POWER JACK SPECIFICATION FOR REFLOW SOLDERING PROCESS

1. Materials and Finish:

1.1 Housing

- ◆ Thermoplastic
- ◆ Color: Black or Optional Color Available on Demand

1.2 Contact

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Contact Area: Optional Tin, Silver, Gold Flash or Nickel plating
- ◆ Solder Area: Tin Plating or Nickel Plating
- ◆ Under-Plating: Nickel over all

1.3 Center Pin

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Nickel Plating

1.4 Shell(option)

- ◆ Alloy (See Material Specifications for Reference)
- ◆ Nickel plating

※ Expiration For Plating: 6 months storage period under non-unpacked parts (40%~60%RH)

2. Rating:

- ◆ Current & Voltage:

Diameter of Center Pin(mm)	Rated voltage (V)	Rated current(A)
3.00mm	24	5

- ◆ Storage & Operating Temperature: -25°C~70°C



3. Electrical Performance:

Item		Test conditions	Performance
3.1	Contact Resistance	EIA-364-23B. Subject specimens to 100 mA maximum and 20 mV maximum dry circuit voltage	50mΩ Max (initial)
3.2	Insulation Resistance	EIA-364-21C. Subject specimens to DC 500V and measure insulation resistance between adjacent contacts, also measure between the contacts and the shield.	100MΩ Min.
3.3	Dielectric Withstanding Voltage	EIA-364-20B. Subject specimens to 500VAC (50—60Hz) for 1 minute between terminals and ground.	No discharge or breakdown

4. Mechanical Performance:

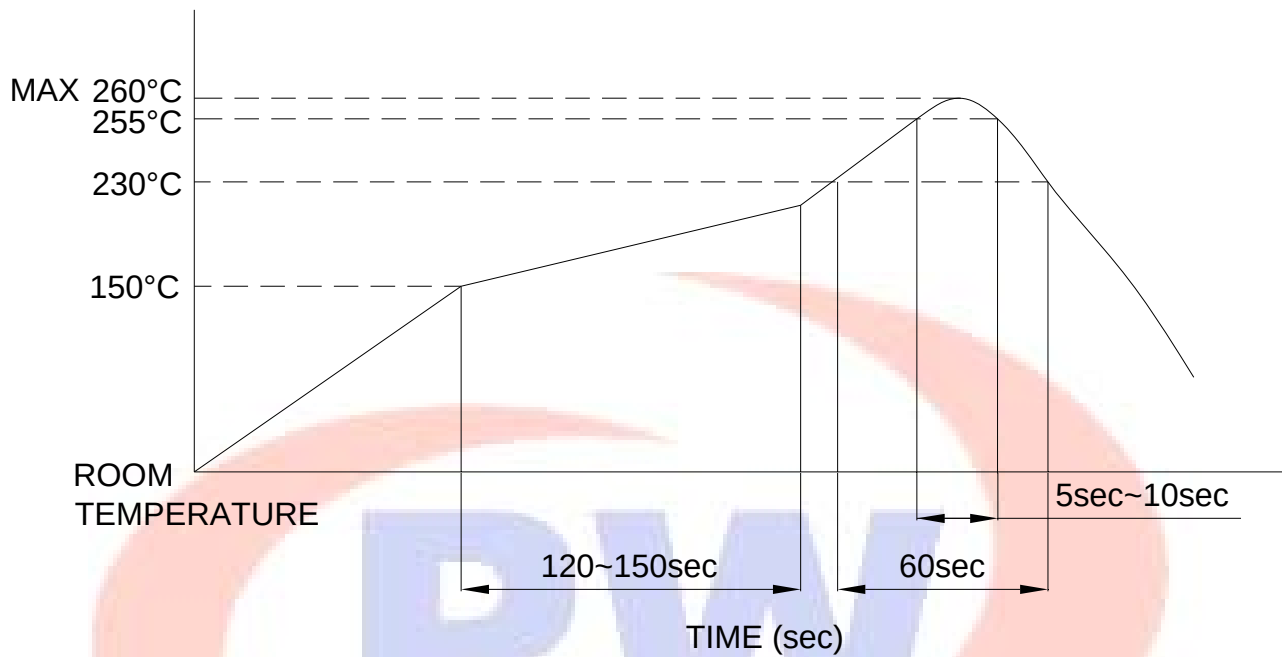
Item		Test conditions	Performance
4.1	Durability	EIA-364-09C. 5,000 cycles operating at a rate of 200±50 cycles per hour , without load.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
4.2	Mating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	30N (Max.)
4.3	Unmating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	3N (Min.)

*5. Environmental Performance:*

Item		Test conditions	Performance
5.1	Heat Test	EIA-364-17B. 70°C±2°C for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.2	Humidity Test	EIA-364-31B. 40°C±2°C, 90-95% RH for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.3	Soldering Heat Resistance Test	EIA-364-56C. Equipment conditions refer to the following recommended reflow soldering profile.	(1) Contact Resistance:100mΩ Max (2) Mechanical and electrical characteristics shall be satisfied.
5.4	Solderability Test	EIA-364-52B. The top of the terminals shall be dipped 2mm in the solder bath of 245°C±5°C for 5±1.0 seconds.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.



REFLOW SOLDERING PROFILE



RECOMMENDED REFLOW SOLDERING CURVE

*6. Test Group and Sequence:*

ITEM	DESCRIPTION	TEST GROUP				
		A	B	C	D	E
		TEST SEQUENCE				
1	Visual inspection	1	1	1	1	1,3
2	Contact Resistance	2,7	2,4	2,4	2,4	
3	Insulation Resistance	3,8				
4	Withstanding Voltage	4,9				
5	Mating & Unmating Force	5,10				
6	Durability	6				
7	Heat Test		3			
8	Humidity Test			3		
9	Soldering Heat Resistance Test				3	
10	Solderability Test					2
Sample Size(pcs)		5	5	5	5	5

Note: